

Docket No. 201841US2/smc



#4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Mitsuo INOUE, et al.  
SERIAL NO: 09/756,191  
FILED: January 9, 2001  
FOR: IMAGING APPARATUS

GAU:  
EXAMINER:

**INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97**

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Applicant(s) wish to disclose the following information.

**REFERENCES**

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

**RELATED CASES**

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

**CERTIFICATION**

- ☐ Each item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

**DEPOSIT ACCOUNT**

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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This publication discloses a techniques for making an imaging apparatus thin by adhering a solid imaging device to a substrate for circuit in an electrically conductive manner in which an opening for imaging area is formed on the substrate for circuit and by adhering the substrate for circuit to an image-forming means. The publication describes on column 5, lines 7 to 22 "On the other hand, the solid imaging device 6 comprises a photoelectric transferring portion 11 formed on a semiconductor substrate, a horizontal scanning shift register 12, vertical scanning shift register 13 and a plurality of terminals 14, wherein driving pulse is supplied to the horizontal and vertical scanning shift registers 12, 13 via the terminals 14 and wherein imaging signals which have been photoelectrically transferred at the photoelectric transferring portion 11 are taken out via the terminals 14. The solid imaging device 6 is mounted on the printed wiring board 7 which is formed of, for example, transparent film-shaped insulating sheet. On the surface of the printed wiring board 7, there are formed a circuit network 15 corresponding to the terminals 14, and an opening 16 corresponding to the photoelectric transferring portion 11. The terminals 14 of the solid imaging device 6 are adhered to the circuit network 15 of the printed wiring board 7 in an electrically conductive manner, and the other portion of the solid imaging device 6 is adhered to the other portion of the printed wiring board 7 by adhesives."

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Group Art Unit:

**Reference AP (JP 10-293236) on Form 1449:**

This publication discloses a technique for making an imaging apparatus thin by making an imaging element contained in lens material, or by making the imaging element closely contact with the lens. The publication describes on column 1, line 46 to column 2, line 2 "According to the solid imaging apparatus of the present invention, the solid imaging device is confined in the lens without interposing air or the like therebetween (i.e. the solid imaging device is not inserted in a lens system, but is directly contained in the material for forming lens), or an imaging surface of the solid imaging device is made contact closely with the lens, thereby a total length of the imaging lens is shortened (so that the lens is miniaturized)."